



ABOUT US

Founded in 1976, Samtec is much more than just another connector company, we put people first with a commitment to exceptional service and quality products. We believe that taking care of our customers and our employees is paramount in how we approach our business. This belief is deeply ingrained throughout Samtec and means that you can expect **exceptional service** coupled with **technologies** that take the industry further faster.

GLOBAL REACH



PRIVATELY

OWNED COMPANY

SUDDEN SERVICE



MORE THAN 200k PART NUMBERS SHIP IN 1 DAY



24-HOUR FREE



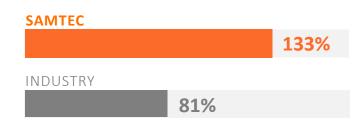
2 DAYS TRANSIT TO ALL MAJOR MARKETS





INDUSTRY UPDATE

SALES GROWTH (10-year span)



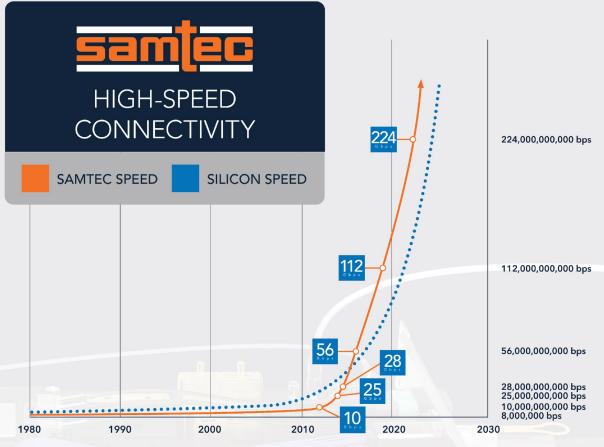
MARKETS SERVED



THE TECHNICAL RENAISSANCE IS...

...driven by **progress**, challenged with unprecedented performance **demands**, a catalyst for next level technologies and **innovation**...





...and enabled by Samtec's

SILICON-TO-SILICON SOLUTIONS

SILICON-TO-SILICON CONNECTIVITY SOLUTIONS





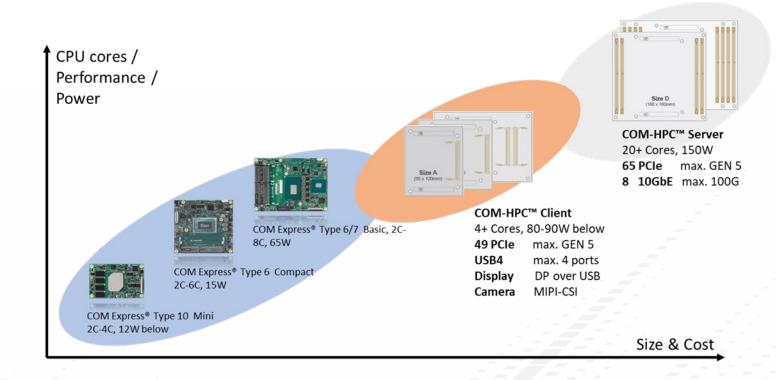
SoM/CoM Evolution

SoM/CoM Concept

- CPU module with standard compute core functions
- Carrier board with customer specific functions & size

SoM/CoM Benefits

- Faster time to market
- Reduced development costs
- Scalable product range
- Allows customer focus on system features
- Faster reaction to market trends
- Second source philosophy
- Minimize inventory cost







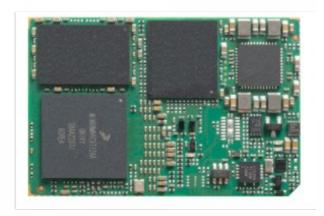
Popular SGET SoM/CoM Solutions













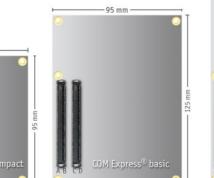


PICMG® COM Express® Overview

Family of modular, small form factor CoM specifications for embedded computing

COM 👉 Express

- One of the most popular embedded hardware standards in the world
- Eight different Types
- Four different sizes
- Three major revisions
- COM Express 3.1 Spec.
- USB4 support for Type 6 designs
- CEI sideband 10 GbE signaling for Type 7 modules
- PCIe 4.0 (16 Gb/s) support across all module types





PICMG® COM-HPC® Overview



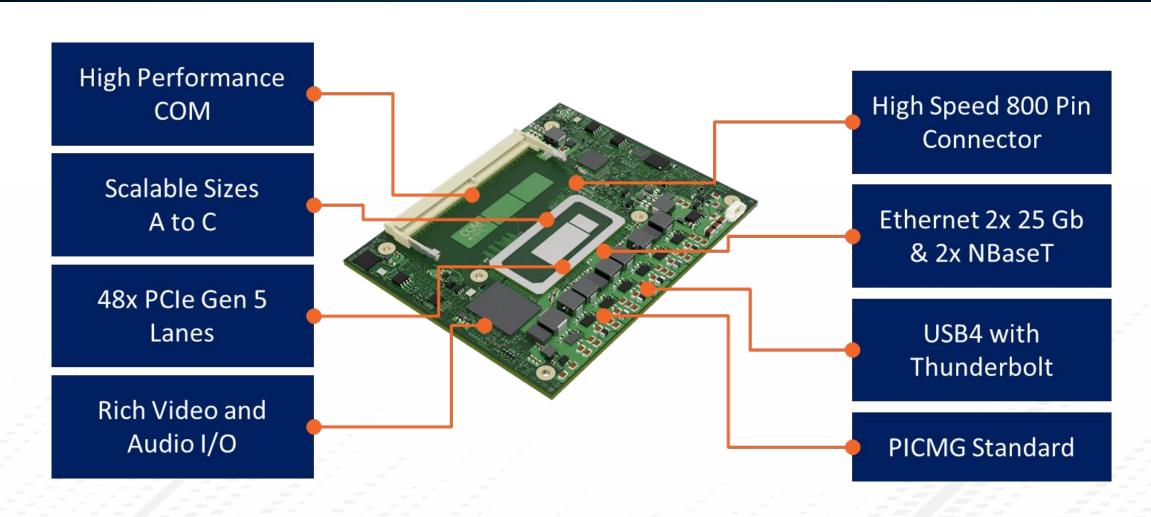
- Why a new standard?
- The COM Express connector is limited
- Max. 32 lanes PCle 3.0 (8 Gb/s)
- Max. 10 Gb Ethernet per signal pair
- COM-HPC target
- Support for PCle 5.0 (32 Gb/s)
- 64 PCle Lanes
- Min. 25 Gb Ethernet per signal pair to support 100 Gb Ethernet
- Update of other interfaces
- COM-HPC will not replace COM Express®
- It extends the Server-On-Module ideas

Feature	сом-нрс	COM Express
Connector Bandwidth	32 Gbps	10 Gbps
Connector Pins	800	440 max
Full size DIMMS	up to 8	up to 2
SO-DIMM Support	up to 4	up to 2
CPU power support	150W	80W
PCIe	up to 5.0	up to 3.0
PCIe lanes	65	32
10G BASE-T	2	1
Ethernet KR interfaces	8 at up to 25 Gbps	up to 4 at 10 Gbps
USB Support	Up to USB4	Up to USB 3.0
Non x86 CPU Support	Yes	No



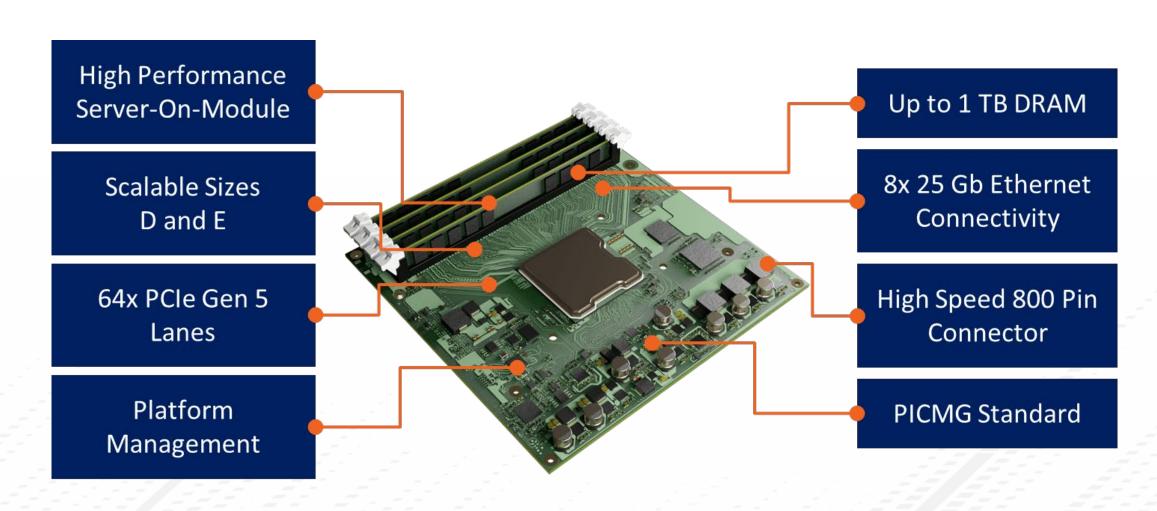


PICMG COM-HPC Client





PICMG COM-HPC Server

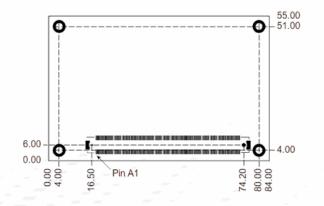




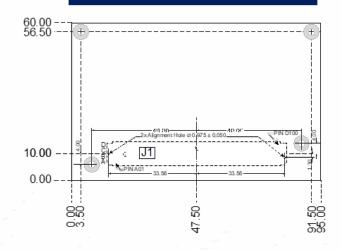
PICMG COM-HPC 1.2 Spec – What's New?

- COM-HPC "Mini"
- Half size "mini" (95 x 60mm) of a Size A
- Define heat spreader and mounting holes
- Remove J2 for the COM-HPC mini definition
- Update J1 pinout → Supports PCle 5.0, 25 GbE, USB4 . . .

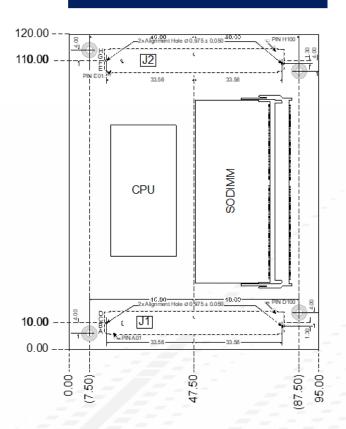
COM Express mini



COM-HPC Size mini



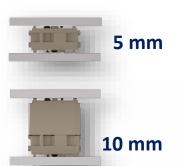
COM-HPC Size A





Samtec COM-HPC Interconnect Solutions

- High-performance, flexible open-pin-field array
- High-speed PCIe 5.0 and 100 Gb Ethernet capable
- 400 pin (4 x 100) BGA mount
- 2.2 / 2.4 / 2.2 mm row pitch
- 0.635 mm pitch
- 5 mm or 10 mm stack heights
- Dimensions: 68.62 mm x 9 mm x stack height
- Up to 360 W at 11.4 12.6 Volts





BGA mount increases density and performance

